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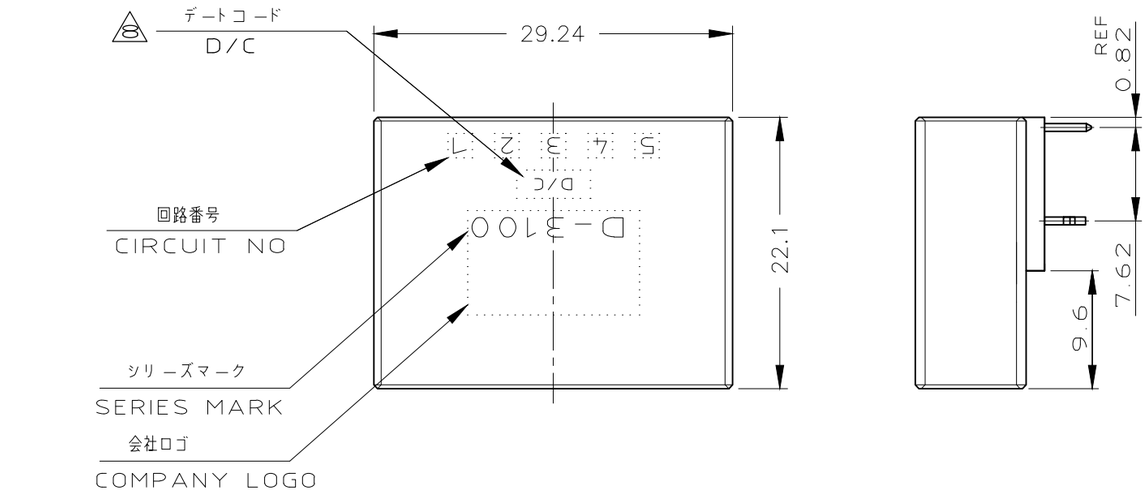
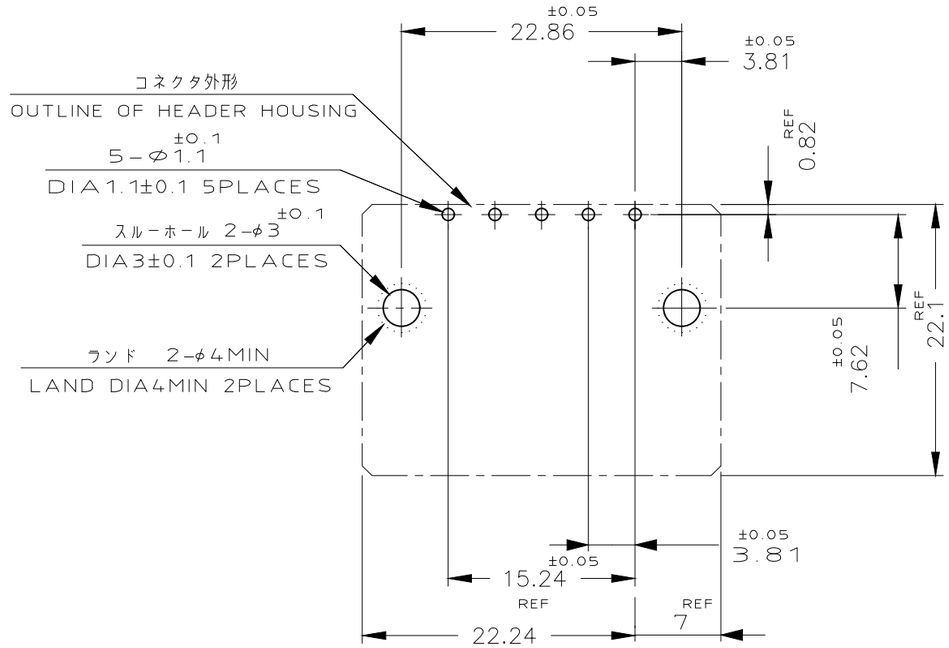
REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
	B2	REVISED PER ECR–18–008681	08JUN2018	K.T	E.I

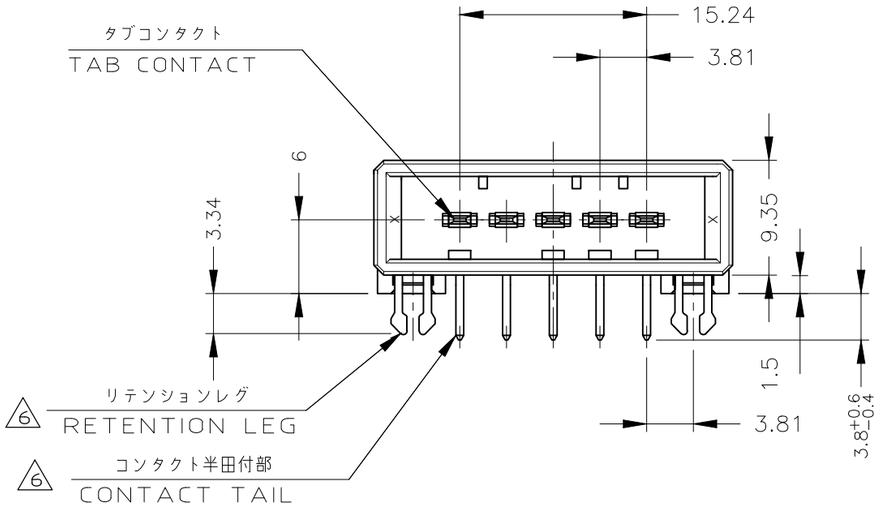




推奨基板取付け穴寸法

PC 基板厚：1.6±0.1
（非累積公差）
（コネクタ搭載面）

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS:1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)



1. MATERIAL:HOUSING:GLASS FILED THERMO PLASTIC,POLYESTER
   CONTACT:COPPER ALLOY
   RETENTION LEG:COPPER ALLOY
2. FINISH(CONTACT AREA):0.38μmMIN GOLD PLATING OVER Ni PLATING
3. FINISH(CONTACT AREA):0.76μmMIN GOLD PLATING OVER Ni PLATING
4. FINISH(CONTACT AREA):2.0μmMIN TIN PLATED OVER NICKEL
5. NOTE DELETED
6. FINISH(RETENTION LEG): TIN PLATED
   (CONTACT TAIL) OVER NICKEL
7. THE SHAPE,SIZE AND POSITION OF THE CHARACTER SHOW THE OUTLINE THEY DON'T SHOW DETAILS
8. THE DATE CODE SHOW PRODUCTION LOT BY NUMBER. THE NUMBER MAKE UP THE NUMBER OF FOUR COLUMS OR FIVE COLUMS. (INCLUDE THE ALPHABET)

1. 材料：ハウジング：ガラス入り熱可塑性ポリエステル樹脂
   コンタクト：銅合金
   リテンションレグ：銅合金
2. めっき：コンタクト：全面 Ni下地
   接触部：0.38μm MIN金めっき
3. めっき：コンタクト：全面 Ni下地
   接触部：0.76μm MIN金めっき
4. めっき：コンタクト：全面 Ni下地
   接触部：2.0μm MINスズめっき
5. NOTE DELETED
6. めっき リテンションレグとコンタクト半田付部 ：ニッケル下地の上にスズめっき
7. 文字の形状、大きさ、および位置については、大略を示すものであり、詳細を示すものではありません
8. 4桁の数字及びアルファベットを含む5桁の数字により製造ロットを示す。

6	4	1–178295–5
6	3	1–178295–3
6	2	1–178295–2
(FINISH)		製品番号 (PART NO.)

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm

TOLERANCES UNLESS OTHERWISE SPECIFIED:

0 PLC	± –
1 PLC	± 0.3
2 PLC	± 0.4
3 PLC	± 0.5
4 PLC	± –
ANGLES	± 3°

MATERIAL: SEE NOTE 注記参照

FINISH: SEE NOTE 注記参照

DWN N. MATSULARA 14 JUN 91
CHK H.OBATA 14 JUN 91
APVD N. MATSULARA 14 JUN 91
PRODUCT SPEC —
APPLICATION SPEC —
WEIGHT

TE Connectivity Ltd.

NAME: 5 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC 3100 —

SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
A3	00779	C–178295	—

CUSTOMER DRAWING | SCALE 1:1 | SHEET 1 OF 1 | REV B2